

SGLS369A-AUGUST 2006-REVISED NOVEMBER 2006

FEATURES

- Controlled Baseline
 - One Assembly Site
 - One Test Site
 - One Fabrication Site
- Extended Temperature Performance of -55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree (1)
- 3-Pin SOT-23 Package
- Supply Current of 9 µA (Typical)
- (1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

DESCRIPTION

The TPS3809 family of supervisory circuits provides circuit initialization and timing supervision, primarily for DSPs and processor-based systems.

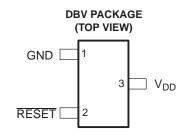
During power-on, $\overline{\text{RESET}}$ is asserted when the supply voltage V_{DD} becomes higher than 1.1 V. Thereafter, the supervisory circuit monitors V_{DD} and keeps $\overline{\text{RESET}}$ active as long as V_{DD} remains below the threshold voltage V_{IT} . An internal timer delays the return of the output to the inactive state (high) to ensure proper system reset. The delay time, $t_{d(typ)} = 200$ ms, starts after V_{DD} has risen above the V_{IT} . When the supply voltage drops below the V_{IT} , the output becomes active (low) again. No external components are required. All the devices of this family have a fixed-sense V_{IT} set by an internal voltage divider.

The product spectrum is designed for supply voltages of 2.5 V, 3 V, 3.3 V, and 5 V. The circuits are available in a 3-pin SOT-23 package. The TPS3809 devices are characterized for operation over a temperature range of –55°C to 125°C.

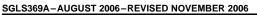


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

- Precision Supply Voltage Monitor 2.5 V, 3 V, 3.3 V, 5 V
- Power-On Reset Generator With Fixed Delay Time of 200 ms
- Pin-for-Pin Compatible With MAX 809

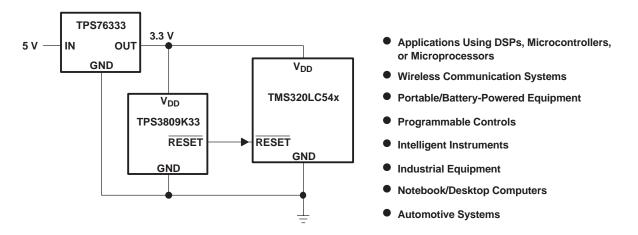


TPS3809L30-EP, TPS3809K33-EP, TPS3809I50-EP 3-PIN SUPPLY VOLTAGE SUPERVISORS





TYPICAL APPLICATIONS



AVAILABLE OPTIONS

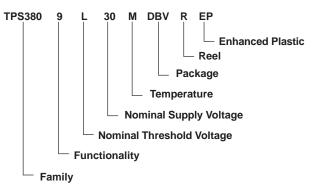
T _A	DEVICE NAME	THRESHOLD VOLTAGE	MARKING
	TPS3809L30MDBVREP ⁽¹⁾	2.64 V	PLYM
–55°C to 125°C	TPS3809K33MDBVREP ⁽¹⁾	2.93 V	PLZM
	TPS3809I50MDBVREP ⁽¹⁾	4.55 V	PMAM

(1) The DBVR passive indicates tape and reel of 3000 parts.

FUNCTION/TRUTH TABLE

$V_{DD} > V_{IT}$	RESET
0	L
1	н

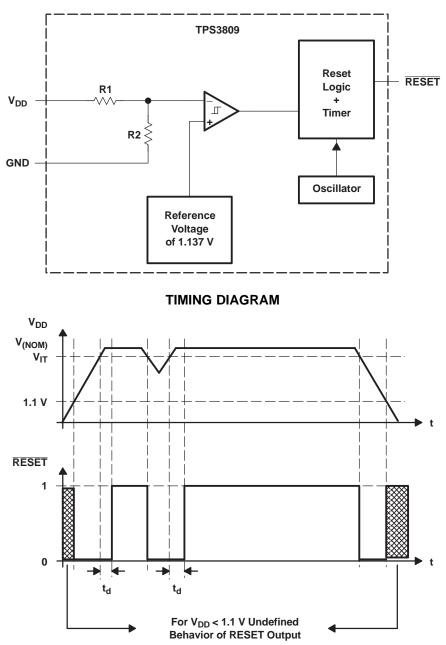
ORDERING INFORMATION



TPS3809L30-EP, TPS3809K33-EP, TPS3809I50-EP 3-PIN SUPPLY VOLTAGE SUPERVISORS

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FUNCTIONAL BLOCK DIAGRAM



TPS3809L30-EP, TPS3809K33-EP, TPS3809I50-EP 3-PIN SUPPLY VOLTAGE SUPERVISORS

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Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
	Supply voltage ⁽²⁾	V _{DD}		7	V
		All other pins	-0.3	7	v
I _{OL}	Maximum low output current			5	mA
I _{OH}	Maximum high output current			-5	mA
I _{IK}	Input clamp current	$V_I < 0 \text{ or } V_I > V_{DD}$		±20	mA
I _{OK}	Output clamp current	$V_0 < 0 \text{ or } V_0 > V_{DD}$		±20	mA
	Continuous total power dissipation		See Di	issipation	Rating Table
T _A	Operating free-air temperature range		-55	125	°C
T _{stg}	Storage temperature range		-65	150	°C
	Soldering temperature			260	°C

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ISTRUMENTS www.ti.com

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values are with respect to GND. For reliable operation the device should not be operated at 7 V for more than t = 1000h continuously.

Dissipation Ratings

PACKAGE	T _A < 25°C	DERATING FACTOR	T _A = 70°C	T _A = 85°C
	POWER RATING	ABOVE T _A = 25°C	POWER RATING	POWER RATING
DBV	437 mW	3.5 mW/°C	280 mW	227 mW

Recommended Operating Conditions

		MIN	MAX	UNIT
V_{DD}	Supply voltage	2	6	V
T _A	Operating free-air temperature	-55	125	°C

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Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			1	EST CONDITION	S	MIN	TY P	MAX	UNIT	
			$V_{DD} = 2.5 V \text{ to } 6 V,$	I _{OH} = -500 μA		V _{DD} - 0.2				
	/ _{OH} High-level output voltage		V _{DD} = 3.3 V,	$I_{OH} = -2 \text{ mA}$		V _{DD} - 0.4			1	
V _{OH}		lage	$V_{DD} = 6 V,$	$I_{OH} = -4 \text{ mA}$		V _{DD} - 0.4			V	
			V _{DD} = 6 V,	$I_{OH} = -4 \text{ mA},$	$T_A = 125^{\circ}C$	V _{DD} – 0.5				
			$V_{DD} = 2 V \text{ to } 6 V,$	I _{OL} = 500 μA				0.2		
V _{OL}	Low-level output v	oltage	V _{DD} = 3.3 V,	$I_{OL} = 2 \text{ mA}$				0.4	V	
			V _{DD} = 6 V,	$I_{OL} = 4 \text{ mA}$				0.4		
	Power-up reset vo	ltage ⁽¹⁾	$V_{DD} \ge 1.1 V$,	I _{OL} = 50 μA				0.2	V	
	TPS3809L30					2.58	2.6 4	2.7		
V _{IT-}	Negative-going input threshold voltage ⁽²⁾	TPS3809K33				2.87	2.9 3	2.99	V	
	. enage	TPS3809150				4.45	4.5 5	4.65		
		TPS3809L30					35			
V _{hys}	hys Hysteresis TPS38						40		mV	
		TPS3809I50					60			
	Supply ourrent		$V_{DD} = 2 V,$	Output unconnec	ted		9	12		
I _{DD}	DD Supply current		$V_{DD} = 6 V,$	Output unconnec	ted		20	25	μA	
Ci	Input capacitance		$V_{I} = 0 V \text{ to } V_{DD}$				5		pF	

The lowest supply voltage at which RESET becomes active. t_r, V_{DD} ≥ 15 µs/V.
To ensure best stability of the threshold voltage, a bypass capacitor (0.1-µF ceramic) should be placed near the supply terminals.

Timing Requirements

 R_{L} = 1 MΩ, C_{L} = 50 pF, T_{A} = 25°C

	PARAMETER	TEST CONDITIONS	MIN MAX	UNIT
tw	Pulse width at V _{DD}	$V_{DD} = V_{IT-} + 0.2 \text{ V}, V_{DD} = V_{IT-} - 0.2 \text{ V}$	3	μs

Switching Characteristics

 R_L = 1 M Ω , C_L = 50 pF, T_A = 25°C

	PARAMET	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
t _d	Delay time	$V_{DD} \ge V_{IT-}$ + 0.2 V, See timing diagram	120	200	280	ms	
t _{PHL}	Propagation (delay) time, high- to low-level output	V _{DD} to RESET delay	$V_{IL} = V_{IT-} - 0.2 V,$ $V_{IH} = V_{IT-} + 0.2 V$		1		ms



85

LOW-LEVEL OUTPUT VOLTAGE **HIGH-LEVEL OUTPUT VOLTAGE** vs VS LOW-LEVEL OUTPUT CURRENT **HIGH-LEVEL OUTPUT CURRENT** 2.75 6.5 $V_{DD} = 2.5 V$ $V_{DD} = 6 V$ 6.0 2.50 /OH – High-Level Output Voltage – V 5.5 VoL – Low-Level Output Voltage – V 2.25 5.0 2.00 4.5 -40°C T_A = 25°C T_A = 1.75 4.0 1.50 3.5 $T_A = \overline{0^{\circ}C}$ 3.0 T_A = 85°C 1.25 T_A = 85°C 2.5 T_A = 0°C 1.00 2.0 0.75 T_A =−40°C 1.5 0.50 1.0 T_A = 25°C 0.25 0.5 0.00 0.0 5.0 0.0 2.5 7.5 10.0 12.5 -10 -20 0 -30 -40 -50 IOL - Low-Level Output Current - mA IOH - High-Level Output Current - mA Figure 2. Figure 1. **HIGH-LEVEL OUTPUT VOLTAGE** NORMALIZED INPUT THRESHOLD VOLTAGE VS vs **HIGH-LEVEL OUTPUT CURRENT** FREE-AIR TEMPERATURE AT VDD 3.00 Normalized Threshold Voltage VIT (TA), VIT (25 $^\circ\text{C})$ 1.001 $V_{DD} = 2.5 V$ V_{DD} = 2.3 V 2.75 VOH – High-Level Output Voltage – V 1.000 2.50 2.25 0.999 2.00 T_A =−40°C 1.75 0.998 1.50 T_A = 0°C 1.25 0.997 1.00 T_A = 85°C 0.75 0.50 T_A = 25°C 0.996 0.25 0.995 0.00 0 -2 -4 -40 -20 20 40 60

TYPICAL CHARACTERISTICS

-10

0

T_A – Free-Air Temperature – °C

Figure 4.

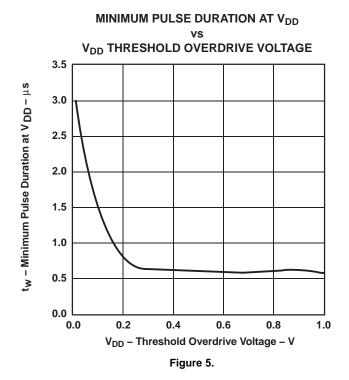
-6

IOH - High-Level Output Current - mA

Figure 3.

-8

TYPICAL CHARACTERISTICS (continued)



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TPS3809I50MDBVREP	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809K33MDBVREP	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809L30MDBVREP	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/06636-01XE	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/06636-02XE	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/06636-03XE	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF TPS3809I50-EP, TPS3809K33-EP, TPS3809L30-EP:

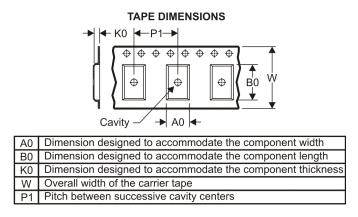
Catalog: TPS3809I50, TPS3809K33, TPS3809L30
Automotive: TPS3809I50-Q1, TPS3809K33-Q1, TPS3809L30-Q1

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

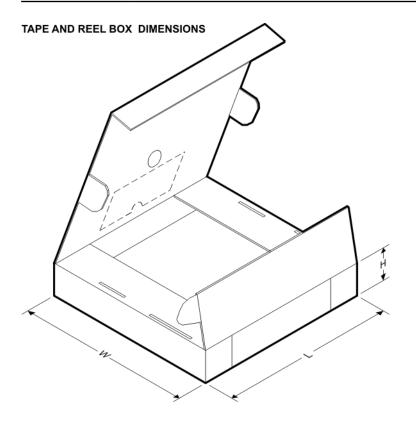


*All dimensions are nominal	All dimensions are nominal											
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3809I50MDBVREP	SOT-23	DBV	3	3000	180.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809K33MDBVREP	SOT-23	DBV	3	3000	180.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809L30MDBVREP	SOT-23	DBV	3	3000	180.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3



PACKAGE MATERIALS INFORMATION

6-Aug-2008

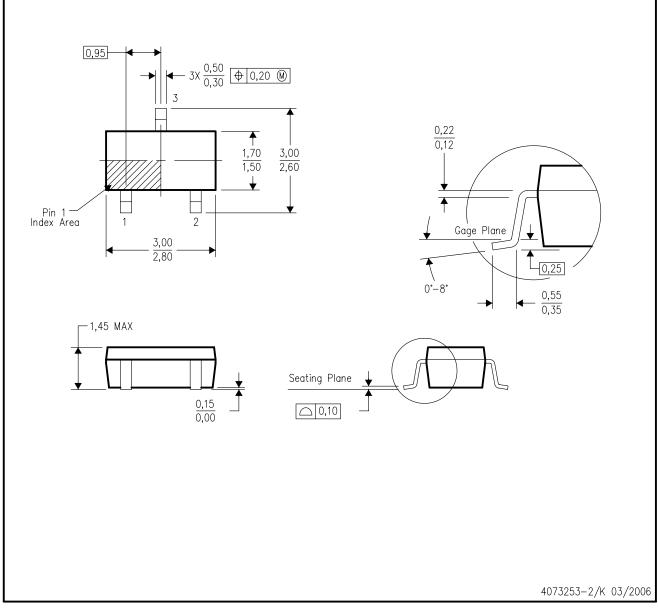


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3809I50MDBVREP	SOT-23	DBV	3	3000	182.0	182.0	20.0
TPS3809K33MDBVREP	SOT-23	DBV	3	3000	182.0	182.0	20.0
TPS3809L30MDBVREP	SOT-23	DBV	3	3000	182.0	182.0	20.0

DBV (R-PDSO-G3)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.



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